MODEL BB1020DT

SCSI Termination Resistor network Low Voltage Differential (LVD)



DISCRIPTION

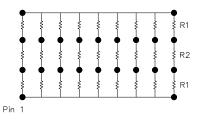
Model BB1020DT is a SCSI LVD termination network designed to terminate high performance SPI-2 (Ultra2) and SPI-3 (Ultra3) bused applications. Wide SCSI bus applications can be terminated with three BB1020DT networks and a linear regulator IC.

For use in high-speed SCSI bus applications, the BB1020DT utilizes thick film resistors on a ceramic substrate with ball grid array (BGA) terminals. Resistors and solder balls reside on the same side of the ceramic substrate, resulting in the absolute minimum stray capacitance and inductance.

FEATURES

- SPI-2 (Ultra2) and SPI-3 (Ultra3) compliant
- Each network contains LVD termination for up to 9 lines
- Superior high frequency performance
- Minimal stray capacitance and inductance
- Surface mountable with automatic pick and place equipment

SCHEMATIC



 $R1 = 475\Omega$ (18 places)

 $R2 = 121\Omega$ (9 places)

ELECTRICAL¹

Resistance Nominal (R1 & R2)	475Ω, 121Ω
Absolute Tolerance	±1%
Temperature Coefficient of Resistance (TCR)	±100 ppm/°C
Interlead Capacitance, Maximum	0.1 pF
Operating Temperature Range	-55°C to +125°C
Power Rating (per network @ 70°C)	1 Watt

Specifications subject to change without notice.

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MODEL BB1020DT

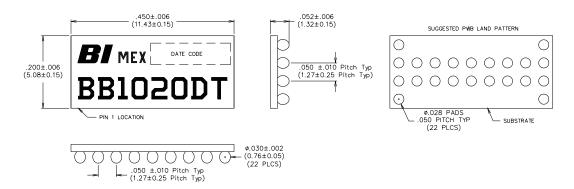
MECHANICAL

Solder Ball Finish (for non-RoHS)	SnPbAg 10/88/2
Solder Ball Co-planarity	0.15 mm
Substrate Material	Al_2O_3
Resistor Material	Cermet

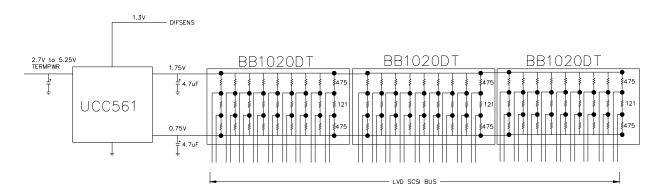
ORDERING INFORMATION ²	Reel Size (inches)	Quantity/Reel	RoHS compliant ³
BB1020DT7	7	1000	No
BB1020DTLF7	7	1000	Yes
BB1020DT13	13	4000	No
BB1020DTLF13	13	4000	Yes

OUTLINE DRAWING

Units: inches / (mm)



APPLICATION NOTES



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² Contact our customer service for custom designs and features.

³ Preliminary release date is Q3 2006.